

Application:

WLAN, 802.11b/g, Bluetooth, etc...

Features

SMD, high reliability, ultra Impact, Omni-directional...



Part number

AAN 2012 F0 P 2G45
 (1) (2) (3) (4) (5)

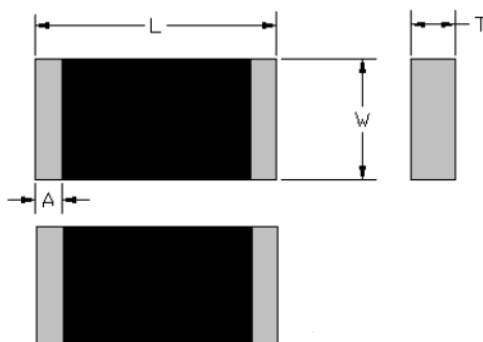
| | |
|------------------|--------------|
| (1)Product Type | Chip Antenna |
| (2)Size Code | 2.0x1.2mm |
| (3)Type Code | F0 |
| (4)Packing | Paper &Reel |
| (5)Frequency | 2.45GHz |
| (6)Internal code | |

Electrical Specification

| | |
|---------------------------|------------------|
| Working Frequency Range | 2400 ~2483MHz |
| Peak Gain | 1.32 dBi (Typ.) |
| Impedance | 50 Ohm |
| Return loss | 10 dB (Min) |
| Polarization | Linear |
| Azimuth Beamwidth | Omni-directional |
| Operation Temperature(°C) | -40 ~85°C |

The specification is defined on EVB.

Dimension and Terminal Configuration



| Dimension (mm) | |
|----------------|-----------|
| L | 2.05±0.15 |
| W | 1.20±0.15 |
| T | 0.50±0.10 |
| A | 0.20±0.10 |

Evaluation Board Reference

| PCB Dimension | Antenna Layout Reference |
|---|--|
| <p style="text-align: center;">Unit :mm</p> | <p>2). PCB Top View :</p> <p>Type1 :</p> |

Electrical Characteristics

Return Loss & Radiation

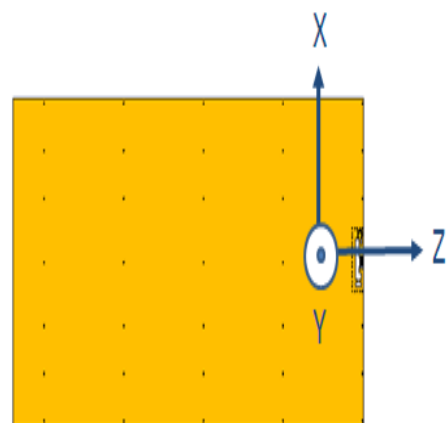
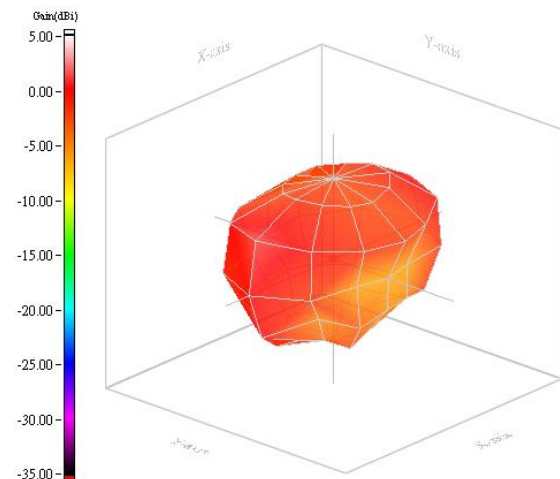
R Trc2 dB Mag 10 dB / Ref 0 dB Invisible 1
 Trc3 dB Mag 10 dB / Ref 0 dB Cal int Offs

| | | | |
|------------|-----|--------------|------------|
| S11 | M 1 | 2.400000 GHz | -10.776 dB |
| | M 2 | 2.442000 GHz | -24.812 dB |
| | M 3 | 2.484000 GHz | -10.243 dB |

Ch1 Start 2 GHz Pwr 0 dBm Stop 3 GHz

| Frequency (MHz) | S11 (dB) |
|-----------------|----------|
| 2400 | -10.78 |
| 2442 | -24.81 |
| 2484 | -10.24 |

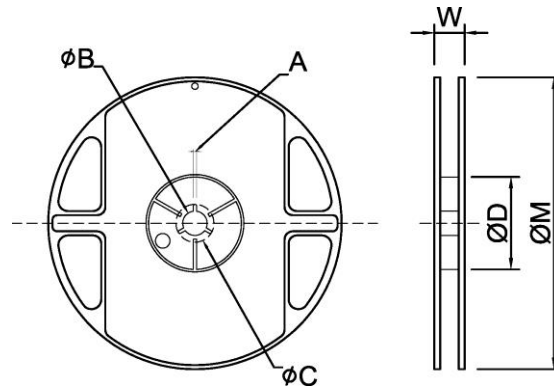
Radiation



Taping Specifications

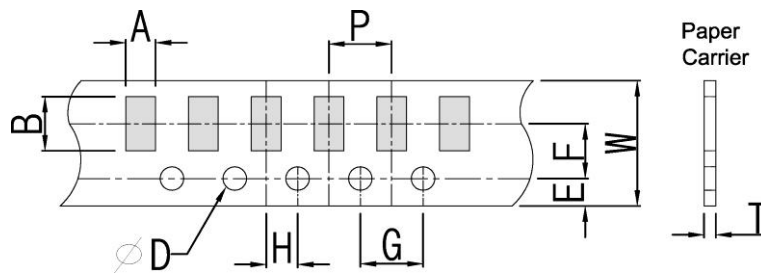
Reel and Taping Specification

Reel Specification



| TYPE | SIZE | | A | ϕB | ϕC | ϕD | W | ϕM |
|------|------|---------|---------|----------|----------|----------|----------|----------|
| 2012 | 7" | 5K/Reel | 2.0±0.5 | 13.5±1.0 | 21±1.0 | 60±1.0 | 11.5±2.0 | 178±2.0 |

Tapping Specification



| Packaging | Type | A | B | W | E | F | G | H | T | ϕD | P |
|------------|------|-----------|-----------|----------|-----------|----------|----------|----------|-----------|---------------------|---------|
| Paper Type | 2012 | 1.90±0.20 | 3.50±0.20 | 8.0±0.20 | 1.75±0.10 | 3.5±0.05 | 4.0±0.10 | 2.0±0.05 | 0.75±0.10 | 1.50 +0.10 -0 | 4.0±0.1 |

Reliability Table

| Test Item | Procedure | Requirements Ceramic Type | Remark (Reference) |
|--|---|---|---------------------------|
| Electrical Characterization | | Fulfill the electrical specification | User Spec. |
| Thermal Shock | 1. Preconditioning: $50 \pm 10^\circ\text{C}$ / 1 hr , then keep for 24 ± 1 hrs at room temp. 2. Initial measure: Spec: refer Initial spec. 3. Rapid change of temperature test: -30°C to $+85^\circ\text{C}$; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature. | No Visible Damage. Fulfill the electrical specification. | MIL-STD-202 107 |
| Temperature Cycling | 1. Initial measure: Spec: refer Initial spec. 2. 100 Cycles (-30°C to $+85^\circ\text{C}$), Soak Mode=1 (2 Cycle/hours). 3. Measurement at 24 ± 2 Hours after test condition. | No Visible Damage. Fulfill the electrical specification. | JESD22 JA104 |
| High Temperature Exposure | 1. Initial measure: Spec: refer Initial spec. 2. Unpowered; 500hours @ $T=+85^\circ\text{C}$. 3. Measurement at 24 ± 2 hours after test. | No Visible Damage. Fulfill the electrical specification. | MIL-STD-202 108 |
| Low Temperature Storage | 1. Initial measure: Spec: refer Initial spec. 2. Unpowered: 500hours @ $T= -30^\circ\text{C}$. 3. Measurement at 24 ± 2 hours after test. | No Visible Damage. Fulfill the electrical specification. | MIL-STD-202 108 |
| Solderability (SMD Bottom Side) | Dipping method: a. Temperature: $235 \pm 5^\circ\text{C}$ b. Dipping time: $3 \pm 0.5\text{s}$ | The solder should cover over 95% of the critical area of bottom side. | IEC 60384-21/22 4.10 |
| Soldering Heat Resistance (RSH) | Preheating temperature: $150 \pm 10^\circ\text{C}$. Preheating time: 1~2 min. Solder temperature: $260 \pm 5^\circ\text{C}$. Dipping time: $5 \pm 0.5\text{s}$ | No Visible Damage. | IEC 60384-21/22 4.10 |
| Vibration | 5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz. | No Visible Damage. | MIL-STD-202 Method 204 |
| Mechanical Shock | Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine | No Visible Damage. | MIL-STD-202 Method 213 |
| Humidity Bias | 1. Humidity: 85% R.H., Temperature: $85 \pm 2^\circ\text{C}$. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2 hrs after test condition. | No Visible Damage. Fulfill the electrical specification. | MIL-STD-202 Method 106 |

| | | | |
|----------------------------------|---|--|-------------------------|
| <p>Board Flex (SMD)</p> | <p>1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm)</p> <p>2. Apply the load in direction of the arrow until bending reaches 2 mm.</p> | <p>No Visible Damage.</p> | <p>AEC-Q200 005</p> |
| <p>Adhesion</p> | <p>Force of 1.8Kg for 60 seconds.</p> | <p>No Visible Damage Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.</p> | <p>AEC-Q200 006</p> |
| <p>Physical Dimension</p> | <p>Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.</p> | <p>In accordance with specification.</p> | <p>JESD22 JB100</p> |

Revision History

| Revision | Date | Content |
|----------|-----------|---|
| 1 | 2015/8/20 | New issue |
| 2 | 2017/4/20 | Update detail dimension on antenna layout |
| 3 | 2018/3/1 | Part number and coding rule updated |